L Number	Hits	Search Text	DB	Time stamp
1	159		USPAT;	2003/11/28 14:19
-	133	semiconductor)) ) and lead) and (method	US-PGPUB;	2000, 22, 20 20121
		process)) and (chip die semiconductor)) and	EPO; JPO;	
		((chip adj select) (clock adj enable))	DERWENT	
2	12		USPAT;	2003/11/28 14:20
		semiconductor)) ) and lead) and (method	US-PGPUB;	
		process)) and (chip die semiconductor)) and	EPO; JPO;	
		((chip adj select) (clock adj enable))) and	DERWENT	
		(straighten\$4 flatten\$4) and (cut cutting		
		shorten\$3)		l
-	1400	257/686	USPAT;	2002/01/15 07:13
			US-PGPUB;	
			EPO; JPO; DERWENT	
	575	257/688	USPAT;	2002/01/15 07:13
-	373	2377 000	US-PGPUB;	2002/01/13 07:13
			EPO; JPO;	
			DERWENT	
_	243	257/689	USPAT;	2002/01/15 07:13
ļ			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	655	257/685	USPAT;	2002/01/15 07:15
			US-PGPUB;	
			EPO; JPO;	
	400	057 /705	DERWENT	2002/01/15 07:15
-	480	257/785	USPAT; US-PGPUB;	2002/01/15 07:15
			EPO; JPO;	ļ
			DERWENT	<b>j</b> .
_	2708	257/686 257/688 257/689 257/685 257/785	USPAT;	2002/01/15 07:15
	2,00	201,000 201,000 201,003 201,000 201,100	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	185	(257/686 257/688 257/689 257/685 257/785)	USPAT;	2002/07/23 13:54
		and ((conductive adj vias) (via adj hole))	US-PGPUB;	
]		and (cavity opening)	EPO; JPO;	
			DERWENT	0000/01/15 07 40
-	23	5043794.URPN.	USPAT;	2002/01/15 07:40
			US-PGPUB; EPO; JPO;	1
			DERWENT	
_	35	5434745.URPN.	USPAT;	2002/01/15 07:44
	33	3434743. OKLIN.	US-PGPUB;	2002, 02, 20 0, 111
			EPO; JPO;	
			DERWENT	
-	69	5128831.URPN.	USPAT;	2002/01/15 07:51
			US-PGPUB;	
]			EPO; JPO;	
		5400004 197 707	DERWENT	2002 (01 (15, 00, 00
-	69	5128831.URPN.	USPAT; US-PGPUB;	2002/01/15 08:00
]			EPO; JPO;	
			DERWENT	
_	4	"5872025"	USPAT;	2002/01/15 08:00
}	· •		US-PGPUB;	
			EPO; JPO;	
	1		DERWENT	
-	2	"6180881"	USPAT;	2002/01/15 08:00
			US-PGPUB;	
			EPO; JPO;	
		WE 5700071	DERWENT	2002/01/15 00:00
-	18	"5579207"	USPAT;	2002/01/15 08:00
			US-PGPUB; EPO; JPO;	
			DERWENT	
_	24	"5872025" "6180881" "5579207"	USPAT;	2002/01/15 08:26
	24	30,2023 0100001 33,720,	US-PGPUB;	= 302, 02, 20 00.20
			EPO; JPO;	
			DERWENT	
	L	<u> </u>	DULITUIT	L

_	16	5579207.URPN.	USPAT; US-PGPUB;	2002/01/15 08:12
			EPO; JPO; DERWENT	2000/07/02 12 47
-	16025	((stacked stack) with (chip semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:47
-	356	(((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:48
<b>-</b>	289	<pre>((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:38
-	289	(((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))) not ("5872025" "6180881" "5579207")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:38
-	107	((((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))) not ("5872025" "6180881" "5579207")) and (ground grounded grounding)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 08:54
-	182	(((((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))) not ("5872025" "6180881" "5579207")) not ((((((stacked stack) with (chip semiconductor))) and ((conductive adj vias) (via adj hole)) and (cavity opening)) not ((257/686 257/688 257/689 257/685 257/785) and ((conductive adj vias) (via adj hole)) and (cavity opening))) not ("5872025" "6180881" "5579207")) and (ground grounded	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 09:22
_	68	grounding)) (((stacked stack) with (chip semiconductor))) and (vertical\$2 near1 connection)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 09:44
-	91	(((stacked stack) with (chip semiconductor))) and (vertical\$2 near1 (mounting connection))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/23 13:51
-	32	5371654.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 09:54
_	2314	257/686 257/688 257/689 257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 12:51
_	325	(257/686 257/688 257/689 257/685) and spring	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 12:52

6 (257/686 257/688 257/689 257/685) and USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/01/15 12:53
EPO; JPO;	
TODAM.	2002/01/15 12:55
- 1 6147411.URPN. USPAT;	2002/01/13 12:33
US-PGPUB; EPO; JPO;	
DERWENT	2002/01/15 13:00
_ 2 6089920.URPN. USPAT;	2002/01/13 13:00
US-PGPUB; EPO; JPO;	
DERWENT	
	2002/01/15 13:01
- 1 6147411.URPN. USPAT; US-PGPUB;	2002/01/13 13:01
EPO; JPO;	
DERWENT	
NODATE.	2002/01/15 13:19
8 (((stacked stack) with (chip USPAT; semiconductor))) and (vertical\$2 near1 US-PGPUB;	2002, 01, 10
surface near1 mount)  semiconductor))) and (vertically hear)  EPO; JPO;	
Surface hear mount/	
_ 85 (((stacked stack) with (chip USPAT;	2002/01/15 13:39
semiconductor))) and ((spring clip) near1 US-PGPUB;	
(contact connection))  Semiconductory) and ((spring crip) near of release,	1
DERWENT	
_ 85 ((((stacked stack) with (chip USPAT;	2002/01/15 13:21
semiconductor))) and ((spring clip) near1 US-PGPUB;	
(contact connection))) not ((((stacked EPO; JPO;	1
stack) with (chip semiconductor))) and DERWENT	
(vertical\$2 near1 connection))	
_ 2   5910885.URPN.   USPAT;	2002/01/15 13:26
US-PGPUB;	
EPO; JPO;	
DERWENT	
- 112 (((stacked stack) with (chip USPAT;	2002/01/15 13:40
semiconductor))) and (((spring clip) near1 US-PGPUB;	
(contact connection)) (clip near spring)) EPO; JPO;	
DERWENT	0000 (01 (15 13 41
- 139 (((stacked stack) with (chip USPAT;	2002/01/15 13:41
semiconductor))) and (((spring clip) near1 US-PGPUB;	
(contact connection)) (leaf near spring)) EPO; JPO; DERWENT	
	2002/01/15 13:41
	2002/01/13 13:11
semiconductor))) and (((spring clip) near1 US-PGPUB; (contact connection)) (leaf near spring) EPO; JPO;	
(contact connection)) (real hear spring)  (clip pear lead))  DERWENT	
(CIIP Hear)	2002/01/15 13:41
- 27 ((((stacked stack) with (chip semiconductor))) and (((spring clip) near1 US-PGPUB;	1 2002, 02, 12
(contact connection)) (clip near spring))) EPO; JPO;	
not (((((stacked stack) with (chip DERWENT	
semiconductor))) and ((spring clip) near1	
(contact connection))) not (((stacked	
stack) with (chip semiconductor))) and	
(vertical\$2 near1 connection)))	
54 ((((stacked stack) with (chip USPAT;	2002/01/15 14:10
semiconductor))) and (((spring clip) near1 US-PGPUB;	
(contact connection)) (leaf near spring))) EPO; JPO;	
not (((((stacked stack) with (chip DERWENT	
semiconductor))) and ((spring clip) near1	
(contact connection))) not ((((stacked	
stack) with (chip semiconductor))) and	
(vertical\$2 near1 connection)))	
18193 ((stacked stack) with (chip semiconductor)) USPAT;	2003/03/23 13:14
US-PGPUB;	
EPO; JPO;	
DERWENT	0000/07/03 13 53
- 445 (((stacked stack) with (chip USPAT;	2002/07/23 13:53
semiconductor)) ) and ((conductive adj US-PGPUB;	1
vias) (via adj hole)) and (cavity opening) EPO; JPO; DERWENT	

			IICDAM.	2002/07/23 13:51
-	17	((((stacked stack) with (chip	USPAT;	2002/07/23 13:51
		semiconductor)) ) and ((conductive adj	US-PGPUB;	
		<pre>vias) (via adj hole)) and (cavity opening))</pre>	EPO; JPO;	
		and (vertical\$2 near1 (mounting	DERWENT	į
		connection))		0000/07/00 10 50
-	206	((((stacked stack) with (chip	USPAT;	2002/07/23 13:53
		semiconductor)) ) and ((conductive adj	US-PGPUB;	
		vias) (via adj hole)) and (cavity opening))	EPO; JPO;	
		and (bump ball bga flipchip (flip adj	DERWENT	
		chip))	rian m	2002/07/22 12:54
-	208	(257/686 257/688 257/689 257/685 257/785)	USPAT;	2002/07/23 13:54
		and ((conductive adj vias) (via adj hole))	US-PGPUB;	
		and (cavity opening)	EPO; JPO;	
			DERWENT	2002/02/22 12:15
-	10172	((stacked stack) near3(chip semiconductor))	USPAT;	2003/03/23 13:15
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	2002/02/22 12:16
-	3259	(((stacked stack) near3(chip	USPAT;	2003/03/23 13:16
		semiconductor)) ) and lead	US-PGPUB;	
			EPO; JPO; DERWENT	İ
		2/31	USPAT:	2003/03/23 13:16
-	2885	((((stacked stack) near3(chip		2003/03/23 13:16
		semiconductor)) ) and lead) and (method	US-PGPUB; EPO; JPO;	
		process)	DERWENT	· ·
	1 401 4	// / 1 1 1 1 1 1 1 2 2 2 2 1 1 1 1 2 2 2 2	USPAT;	2003/03/23 13:16
-	14814	((stacked stack) near3 (chip package	US-PGPUB;	2003/03/23 13:16
		semiconductor))	EPO; JPO;	
			DERWENT	
	4100	(((stacked stack) near3 (chip package	USPAT;	2003/03/23 13:16
-	4189	(((Stacked Stack) hears (chip package   semiconductor)) ) and lead	US-PGPUB;	2003/03/23 13:10
		Semiconductor)	EPO; JPO;	
			DERWENT	
	3605	((((stacked stack) near3 (chip package	USPAT;	2003/03/23 13:19
-	3603	semiconductor)) ) and lead) and (method	US-PGPUB;	2003, 03, 23 13.13
		process)	EPO; JPO;	
		Process,	DERWENT	
_	3278	(((((stacked stack) near3 (chip package	USPAT;	2003/03/23 13:20
	2210	semiconductor)) ) and lead) and (method	US-PGPUB;	
		process)) and (chip die semiconductor)	EPO; JPO;	
1		brocess), and (surf. are sources.	DERWENT	
	. 233	((((((stacked stack) near3 (chip package	USPAT;	2003/03/23 13:21
	. 255	semiconductor)) and lead) and (method	US-PGPUB;	
		process)) and (chip die semiconductor)) and	EPO; JPO;	
		(tsop (thin adj small adj outline adj	DERWENT	
		package))	1	
_	35	((((((stacked stack) near3 (chip package	USPAT;	2003/03/23 16:21
	- 0	semiconductor))) and lead) and (method	US-PGPUB;	]
		process)) and (chip die semiconductor)) and	EPO; JPO;	1
		(tsop (thin adj small adj outline adj	DERWENT	
		package))) and ((chip adj select) (clock		
]		adj enable))	1	
-	28	5455740.URPN.	USPAT	2003/03/23 14:34
	1		USPAT	2003/03/23 14:36

	F 2	("Re36229"   "4956694"   "5138438"	TTO DAM	1 2002 (02 (02 14 27
-	52	1 , 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USPAT	2003/03/23 14:37
		, ,		
		"5369056"   "5369058"   "5371866"     "5377077"   "5420751"   "5446620"		
		"5448450"   "5455740"   "5479318"		
		"5484959"   "5493476"   "5498906"		:
		"5499160"   "5512783"   "5528075"		
		"5543664"   "5550711"   "5552963"		
		"5561591"   "5566051"   "5572065"		
		"5581121"   "5585668"   "5586009"		
		"5588205"   "5592364"   "5605592"		
		"5612570"   "5615475"   "5631193"		
		"5654877"   "5702985"   "5778522"		
		"5783464"   "5801437"   "5804870"		
		"5811877"   "5828125"   "5843807"		
		"5864175"   "5869353"   "5895232"		
İ		"5945732").PN.		
-	4	5778522.URPN.	USPAT	2003/03/23 14:39
-	16	'	USPAT	2003/03/23 14:40
		"5057026"   "5236117"   "5279029"		
İ		"5279991"   "5281852"   "5367766"		
		"5394010"   "5475920"   "5499160"		
		"5514907"   "5523619"   "5543664"		
_	10	"5592364").PN. 5811877.URPN.	HCDAM	2002/02/22 14:45
1_	6	3811877.0RPN.   ("4620215"   "5068712"   "5157478"	USPAT USPAT	2003/03/23 14:46 2003/03/23 14:47
	0	"5299092"   "5394010"   "5554886").PN.	USPAI	2003/03/23 14:47
_	11	3299092	USPAT;	2003/03/23 16:06
		0012.00	US-PGPUB;	2003/03/23 10:00
			EPO; JPO;	
			DERWENT	
_	25	"5760471"	USPAT;	2003/03/23 16:12
			US-PGPUB;	2000,00,20 20122
			EPO; JPO;	
			DERWENT	
-	0	6262476.URPN.	USPAT	2003/03/23 16:16
-	7	("4696525"   "5138438"   "5323060"	USPAT	2003/03/23 16:16
		"5479318"   "5508563"   "5530292"		
		"5760471").PN.		
-	0	6213747.URPN.	USPAT	2003/03/23 16:18
_	30	("3404454"   "4682270"   "4778641"	USPAT	2003/03/23 16:18
•		"5095402"   "5172214"   "5200364"		
		"5214845"   "5331235"   "5418189"		
		"5436500"   "5466887"   "5471369"   "5475259"   "5483024"   "5486720"		
		"5493153"   "5498902"   "5508565"		
		"5519251"   "5527743"   "5530286"		
		"5530292"   "5535509"   "5554823"		ļ i
		"5554886"   "5570272"   "5572068"		
		"5679978"   "5760471"   "6007317").PN.		
-	122	(((((stacked stack) near3 (chip package	USPAT;	2003/11/28 14:19
1		semiconductor))) and lead) and (method	US-PGPUB;	
		process)) and (chip die semiconductor)) and	EPO; JPO;	
1		((chip adj select) (clock adj enable))	DERWENT	
j -	8	((((((stacked stack) near3 (chip package	USPAT;	2003/11/28 14:20
		semiconductor)) ) and lead) and (method	US-PGPUB;	
		process)) and (chip die semiconductor)) and	EPO; JPO;	
		((chip adj select) (clock adj enable))) and	DERWENT	
		(straighten\$4 flatten\$4) and (cut cutting		
		shorten\$3)		
_	114	(((((((stacked stack) near3 (chip package	USPAT;	2003/03/23 16:54
		semiconductor))) and lead) and (method	US-PGPUB;	
		process)) and (chip die semiconductor)) and	EPO; JPO;	
		((chip adj select) (clock adj enable))) not	DERWENT	
		(((((((stacked stack) near3 (chip package		
		<pre>semiconductor)) ) and lead) and (method process)) and (chip die semiconductor)) and</pre>		
		((chip adj select) (clock adj enable))) and		
		(straighten\$4 flatten\$4) and (cut cutting		
ŀ		shorten\$3))		
	<u> </u>	DROT COMPO / /	L	

	81	<pre>((((((((stacked stack) near3 (chip package semiconductor)) ) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) not ((((((((stacked stack) near3 (chip package semiconductor)) ) and lead) and (method process)) and (chip die semiconductor)) and ((chip adj select) (clock adj enable))) and (straighten\$4 flatten\$4) and (cut cutting shorten\$3))) not (((((((stacked stack) near3 (chip package semiconductor))) and lead) and (method process)) and (chip die semiconductor)) and (tsop (thin adj small adj outline adj package))) and ((chip adj select) (clock adj enable)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:54
-		5648681.URPN. ("5276352"   "5424576"   "5457341").PN. "6208021"	USPAT USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/23 16:56 2003/03/23 16:56 2003/03/23 16:59
	47	(US-6297548-\$ or US-5857858-\$ or US-5600541-\$ or US-5579207-\$ or US-5434745-\$ or US-5838060-\$ or US-5995379-\$ or US-6314013-\$ or US-6255726-\$ or US-6195268-\$ or US-6180881-\$ or US-5872025-\$ or US-6147411-\$ or US-5371654-\$ or US-6210993-\$ or US-5910010-\$ or US-6472734-\$ or US-6462408-\$ or US-6252299-\$ or US-5978227-\$ or US-5811877-\$ or US-5631193-\$ or US-5605592-\$ or US-543476-\$ or US-5484959-\$ or US-5493476-\$ or US-5484959-\$ or US-5493476-\$ or US-5895232-\$ or US-5801437-\$ or US-5895232-\$ or US-5404662-\$ or US-5778522-\$ or US-5801437-\$ or US-5588205-\$ or US-5592364-\$ or US-5512783-\$ or US-5138438-\$ or US-6205654-\$ or US-5394010-\$ or US-6084293-\$ or US-628352-\$ or US-66084293-\$ or US-6424031-\$ or US-6424476-\$ or US-6424031-\$ or US-6262676-\$ or US-6262676-\$ or US-648681-\$).did.	USPAT	2003/03/24 07:09
_	15	l	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/24 07:17
-	0	(("not" no) near (connected connection)) with (connected connection connecting) with (clock adj enable)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/24 07:22
	9819	(("not" "no") adj (connected connection))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/24 07:21
_	0	((("not" "no") adj (connected connection))) with (connected connection connecting) with (clock adj enable)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/24 07:22

_	47	(US-5371654-\$ or US-5138438-\$ or	USPAT	2003/07/21 10:24
	1	US-5394010-\$ or US-6472734-\$ or		
		US-6518659-\$ or US-6252299-\$ or		
		US-6462408-\$ or US-6459148-\$ or		
		US-6424031-\$ or US-6404662-\$ or		
		US-6265660-\$ or US-6297548-\$ or		
		US-6399420-\$ or US-6314013-\$ or		
		US-6262476-\$ or US-6255726-\$ or		
		US-6242285-\$ or US-6205654-\$ or		
		US-6210993-\$ or US-6147411-\$ or		
		US-6084293-\$ or US-6195268-\$ or		
		US-6180881-\$ or US-5910010-\$ or		
		US-6028352-\$ or US-5978227-\$).did. or		l i
		(US-5995379-\$ or US-5872025-\$ or		
		US-5857858-\$ or US-5895232-\$ or		
		US-5811877-\$ or US-5838060-\$ or		
		US-5801437-\$ or US-5778522-\$ or		
		US-5648681-\$ or US-5631193-\$ or		
		US-5605592-\$ or US-5588205-\$ or		
		US-5592364-\$ or US-5600541-\$ or		
		US-5512783-\$ or US-5579207-\$ or		
		US-5543664-\$ or US-5493476-\$ or		
		US-5434745-\$ or US-5455740-\$ or		
		US-5484959-\$).did.		
_	1	6472734.URPN.	USPAT	2003/07/21 10:25
	3	("5490324"   "6291259"   "6172432").PN.	USPAT	2003/07/21 10:25
	4	6297548.URPN.	USPAT	2003/07/21 10:23